



SEMITOP[®] 2

IGBT Module

SK45GB063

SK45GAL063

SK45GAR063

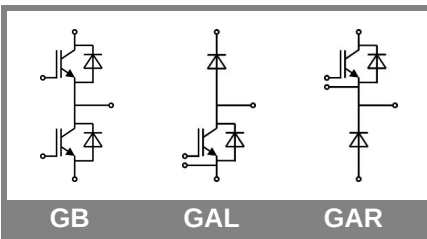
Preliminary Data

Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- N channel, homogeneous Silicon structure (NPT-Non punchthrough IGBT)
- High short circuit capability
- Low tail current with low temperature dependence
- UL recognized, file no. E63532

Typical Applications*

- Switching (not for linear use)
- Inverter
- Switched mode power supplies
- UPS



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Absolute Maximum Ratings				$T_s = 25\text{ °C}$, unless otherwise specified	
Symbol	Conditions			Values	Units
IGBT					
V_{CES}	$T_j = 25\text{ °C}$			600	V
I_C	$T_j = 125\text{ °C}$	$T_s = 25\text{ °C}$		45	A
		$T_s = 80\text{ °C}$		30	A
I_{CRM}	$I_{CRM} = 2 \times I_{Cnom}$			100	A
V_{GES}				± 20	V
t_{psc}	$V_{CC} = 300\text{ V}$; $V_{GE} \leq 20\text{ V}$; $T_j = 125\text{ °C}$ $V_{CES} < 600\text{ V}$			10	μs

Inverse Diode					
I_F	$T_j = 150\text{ °C}$	$T_s = 25\text{ °C}$		57	A
		$T_s = 80\text{ °C}$		38	A
I_{FRM}					A
I_{FSM}	$t_p = 10\text{ ms}$; half sine wave	$T_j = 150\text{ °C}$		440	A

Freewheeling Diode					
I_F	$T_j = 150\text{ °C}$	$T_s = 25\text{ °C}$		57	A
		$T_s = 80\text{ °C}$		38	A
I_{FRM}					A
I_{FSM}	$t_p = 150\text{ ms}$; $T_j = \text{°C}$			440	A

Module					
$I_{t(RMS)}$					A
T_{vj}				-40 ... +150	°C
T_{stg}				-40 ... +125	°C
V_{isol}	AC, 1 min.			2500	V

Characteristics				$T_s = 25\text{ °C}$, unless otherwise specified		
Symbol	Conditions			min.	typ.	max. Units
IGBT						
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 1\text{ mA}$			4,5	5,5	6,5 V
I_{CES}	$V_{GE} = 0\text{ V}$, $V_{CE} = V_{CES}$	$T_j = 25\text{ °C}$				0,15 mA
		$T_j = 125\text{ °C}$				mA
I_{GES}	$V_{CE} = 0\text{ V}$, $V_{GE} = 30\text{ V}$	$T_j = 25\text{ °C}$ $T_j = 125\text{ °C}$				120 nA nA
V_{CE0}		$T_j = 25\text{ °C}$			1	V
		$T_j = 125\text{ °C}$			1,1	V
r_{CE}	$V_{GE} = 15\text{ V}$	$T_j = 25\text{ °C}$			20	mΩ
		$T_j = 125\text{ °C}$				mΩ
$V_{CE(sat)}$	$I_{Cnom} = 50\text{ A}$, $V_{GE} = 15\text{ V}$	$T_j = 25\text{ °C}_{chiplev.}$			2,1	2,5 V
		$T_j = 125\text{ °C}_{chiplev.}$				V
C_{ies}	$V_{CE} = 25$, $V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$			2,2	nF
C_{oes}						nF
C_{res}					0,2	nF
Q_G	$V_{GE} = 0 \dots 20\text{ V}$				155	nC
$t_{d(on)}$	$R_{Gon} = 22\text{ }\Omega$	$V_{CC} = 300\text{ V}$ $I_C = 30\text{ A}$			45	ns
t_r					35	ns
E_{on}	$R_{Goff} = 22\text{ }\Omega$	$T_j = 125\text{ °C}$			1,4	mJ
$t_{d(off)}$		$T_j = 125\text{ °C}$			250	ns
t_f		$V_{GE} = \pm 15\text{ V}$			25	ns
E_{off}					1,2	mJ
$R_{th(j-s)}$	per IGBT					1 K/W



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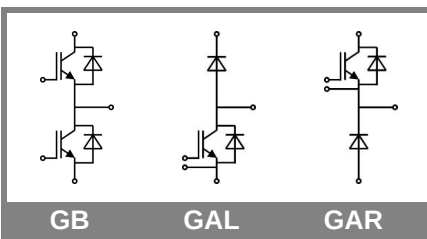
Typical Applications*

- Switching (not for linear use)
- Inverter
- Switched mode power supplies
- UPS

Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
Inverse Diode					
$V_F = V_{EC}$	$I_{Fnom} = 30 \text{ A}; V_{GE} = 0 \text{ V}$		$T_j = 25 \text{ }^{\circ}\text{C}_{chiplev.}$ $T_j = 125 \text{ }^{\circ}\text{C}_{chiplev.}$	1,45 1,4	1,7 1,75 V
V_{F0}			$T_j = 125 \text{ }^{\circ}\text{C}$	0,85	0,9 V
r_F			$T_j = 125 \text{ }^{\circ}\text{C}$	9	16 mΩ
I_{RRM}	$I_F = 30 \text{ A}$		$T_j = 125 \text{ }^{\circ}\text{C}$	16	A
Q_{rr}	$di/dt = -500 \text{ A}/\mu\text{s}$			2	μC
E_{rr}	$V_{CC}=300\text{V}$			0,25	mJ
$R_{th(j-s)D}$	per diode			1,2	K/W
Freewheeling Diode					
$V_F = V_{EC}$	$I_{Fnom} = 30 \text{ A}; V_{GE} = 0 \text{ V}$		$T_j = 25 \text{ }^{\circ}\text{C}_{chiplev.}$ $T_j = 125 \text{ }^{\circ}\text{C}_{chiplev.}$	1,45 1,4	1,7 1,75 V
V_{F0}			$T_j = 125 \text{ }^{\circ}\text{C}$	0,85	0,9 V
r_F			$T_j = 125 \text{ }^{\circ}\text{C}$	9	16 V
I_{RRM}	$I_F = 30 \text{ A}$		$T_j = 125 \text{ }^{\circ}\text{C}$	16	A
Q_{rr}	$di/dt = -500 \text{ A}/\mu\text{s}$			2	μC
E_{rr}	$V_{CC}=300\text{V}$			0,25	mJ
$R_{th(j-s)FD}$	per diode			1,2	K/W
M_s	to heat sink			2	Nm
w				19	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

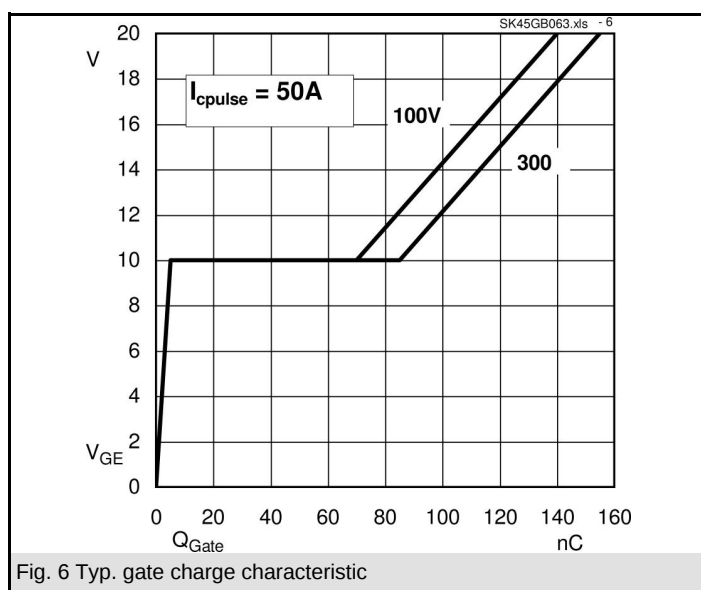
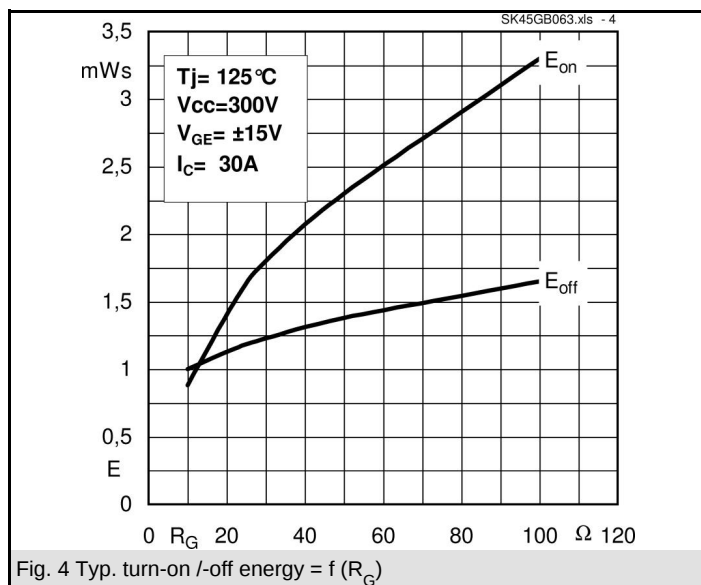
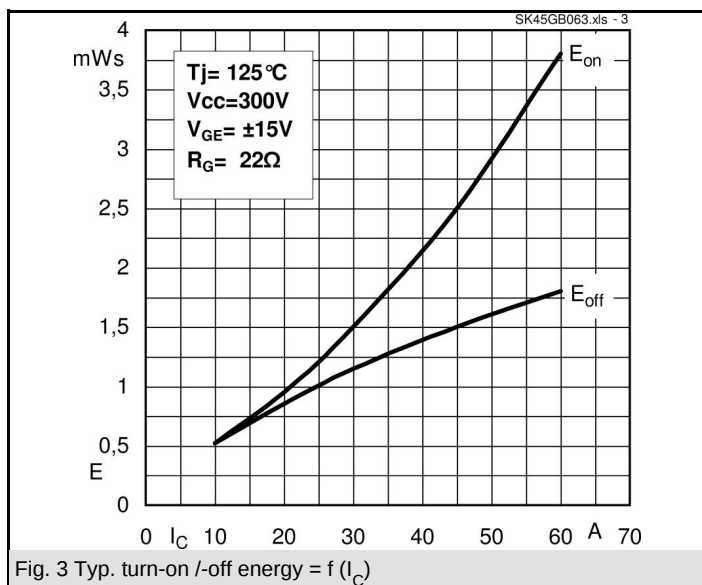
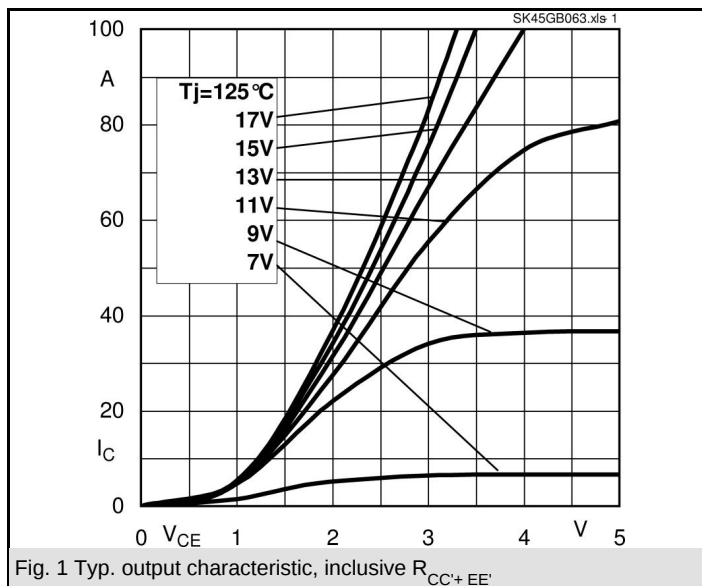
* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.

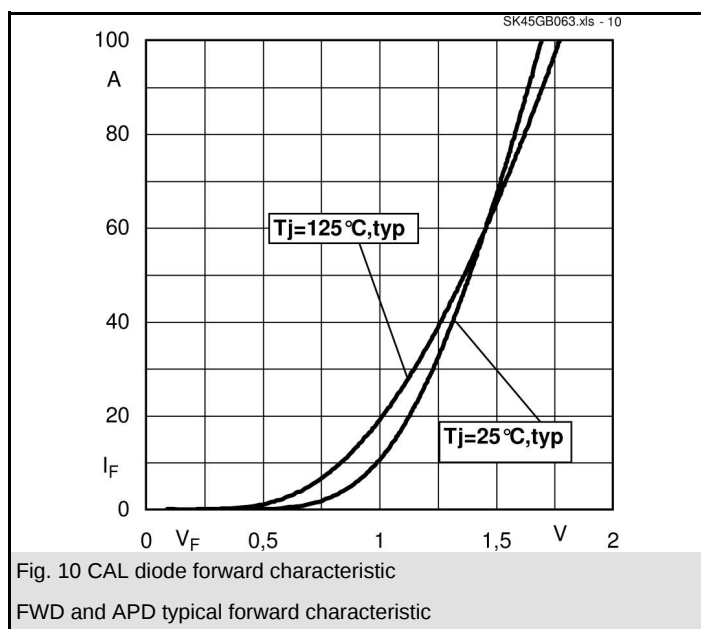
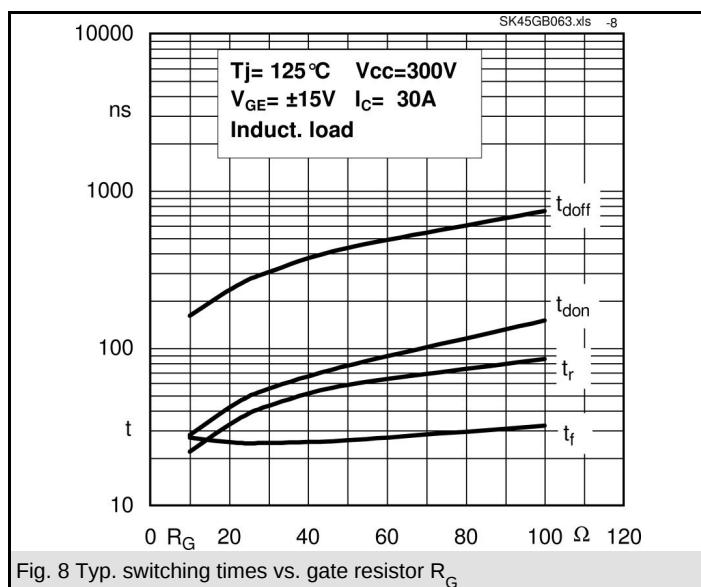
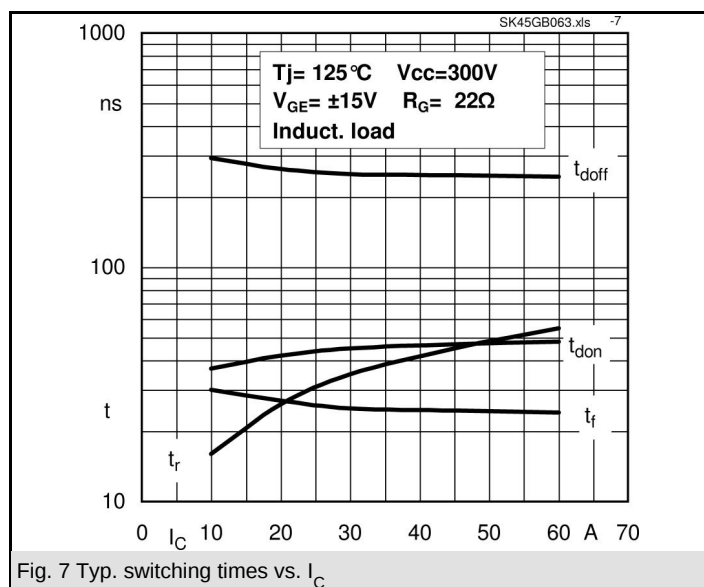


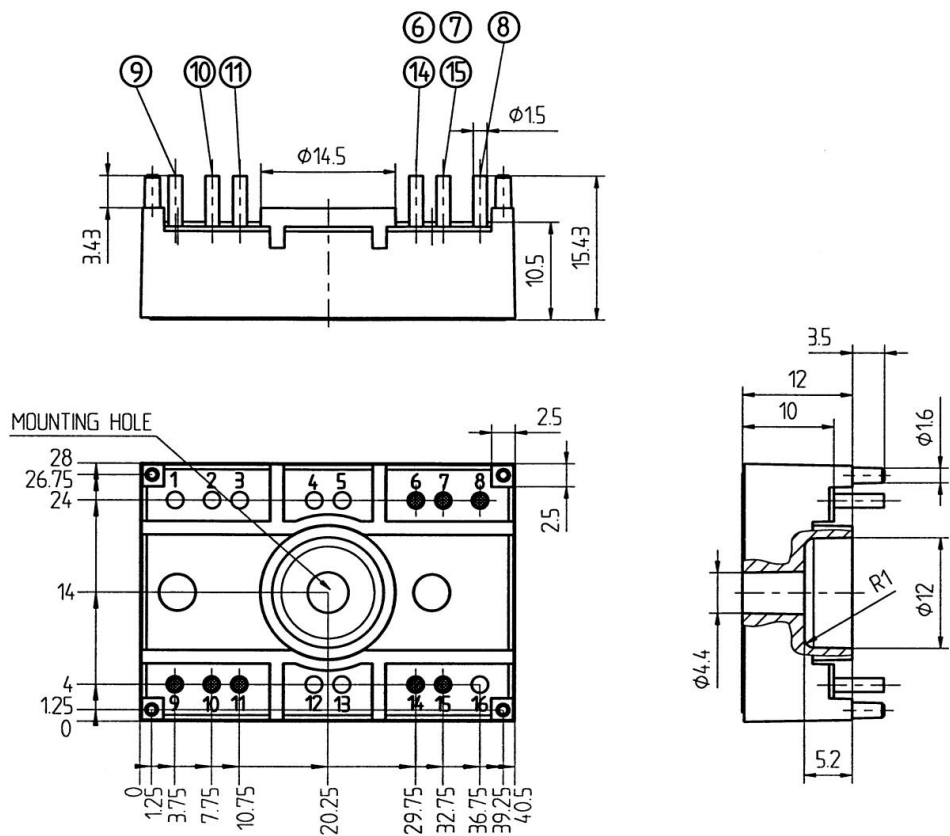
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Case T4 (Suggested hole diameter, in the PCB, for solder pins and plastic mounting pins: 2mm)

